tyco

Electronics

108-57612

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Non ZIF FFC/FPC 1.0&1.25mm Pitch Connector

1. SCOPE

1.1. CONTENTS

This specification covers the performance, tests and quality requirements for the Non ZIF FFC/FPC 1.0/1.25mm Pitch Connector.

1.2. QUALIFICATION

When tests are performed on the subject product line, the procedures specified in Tyco 109 series specifications shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

2. APPLICABLE DOCUMENT

The following Tyco documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the requirements of this specification and the requirements, this specification shall take precedence.

2.1. TYCO SPECIFICATIONS

A. 109-1: General Requirements for Test Specifications

Product

Specification

B. 109-197 : Tyco Specification vs EIA and IEC Test Methods

C. 501-57711 : Test Report

3. REQUIREMENTS

3.1. DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. MATERIALS

A. Housing : Thermoplastic or Thermoplastic High Temp., UL94V-0

B. Contact : Copper Alloy, Tin or Tin-Lead Plated all over and Nickel underplating overall.

3.3. RATINGS

- A. Voltage: 150 VAC rms.
- B. Current: 0.5 A Max
- C. Temperature: 55 °C to 85 °C

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3.4. PERFOMANCE REQUEIREMENT AND TEST DESCRIPTION

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. All tests shall be performed at ambient environmental conditions per AMP Specification 109-1TEST REQUIREMENTS AND PROCEDURES SUMMARY.

3.5. TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST ITEM		REQUIREMENT	PROCEDURE						
1	Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection.						
	ELECTRICAL REQUIREMENT								
2	Contact Resistance	20 m Ohm Max(Initial) 30 m Ohm Max(Final)	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max. EIA-364-6B.						
3	Dielectric withstanding Voltage	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX	500 VAC for 1minute Test between adjacent circuits of unmated connector. EIA-364-20B						
4	Insulation Resistance	1000 M Ohm Min.	Impressed voltage 500 VDC. Test between adjacent circuits of unmated connector. EIA-364-21C.						
		MECHANICAL REQUIREN	NENT						
5	Connector Mating Force	150 gram/Pin Max.	Operation Speed : 25 mm/min. Measure the force required to mate connector. EIA-364-13B						
6	Connector Unmating Force	40 gram/Pin Min	Operation Speed : 25 mm/min. Measure the force required to unmate connector. EIA-364-13B						
7	Durability	See Notes	Operation Speed : 500 cycle/hour. Durability Cycles : 20 cycles EIA-364-9C						
8	Contact Retention Force	0.4 Kgf/Pin Min.	Measure the contact force with Tensile strength tester.						
9	Solderability [Apply to wave soldering process. See note 2]	The inspected area of each lead must have 95% solder coverage minimum.	Steam Aging Preconditioning : $93+3/-5^{\circ}$ 8hrs±15min <jesd22-b012d, c="" condition=""> Dip temperature: 245±5°C, 5sec</jesd22-b012d,>						
	Solderability [Apply to IR soldering process. See note 2]	The inspected area of each lead must have 95% solder coverage minimum.	Steam Aging Preconditioning : 93+3/-5℃ 、8hrs±15min <jesd22-b012d, c="" condition=""> Reflow 230-245℃, 50-70s.</jesd22-b012d,>						

Figure 1 (Cont.)



	ENVIRONMENTAL REQUIREMENTS						
10	Resistance to Wave Soldering Heat [Apply with customer Drawing notes. See note 2]	No physical damage shall occur.	Solder Temp: 265±5℃,10±0.5sec. Tyco spec. 109-202, Condition B				
	Resistance to Reflow Soldering Heat [Apply with customer Drawing notes. See note 2]	No physical damage shall occur.	Pre-soak condition, 85° C/ 85° RH for 168 hours. Pre Heat : $150 \sim 180^{\circ}$ C, 90 ± 30 sec. Heat : 230° C Min., 30 ± 10 sec. Peak Temp. : $260 \pm 0/-5^{\circ}$ C, $20 \sim 40$ sec. Duration : 3 cycles Tyco spec. 109-201, Condition B				
11	Humidity-Terperature Cycle	See Notes	Mated Connector 25℃~65℃, 90~95% RH, 10 Cycle EIA-364-31B				
12	Salt Spray	No detrimental corrosion allowed in contact area and base metal exposed.	Subject mated connectors to $35+/-2^{\circ}C$ and $5+/-1^{\circ}$ salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B.				

Figure 1 (End)

Note 1 : Shall meet visual requirements, show no physical damage, and meet requirement of additional tests as specified in the test sequence in Figures 2

Note 2 : Soldering process is indicated on customer drawing notes. Select the appropriate optional which is compliant with customer drawing's.



3.6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST

	Test Group				
Test or Examination	Α	B	C	D	E
	Test Sequence (a)				
Examination of Product	1, 4	1, 9	1, 5	1, 3	1, 3
Contact Resistance		2, 8	2, 4		
Dielectric withstanding Voltage	3				
Insulation Resistance	2				
Mating Force		3, 7			
Unmating Force		4, 6			
Durability		5			
Contact Retention Force				4	
Solderability					2
Resistance to Soldering Heat				2	
Salt Spray			3		

Figure 2

NOTE : (a) Numbers indicate sequence in which tests are performed.

(b) Discontinuities shall not take place in this test group, during tests.